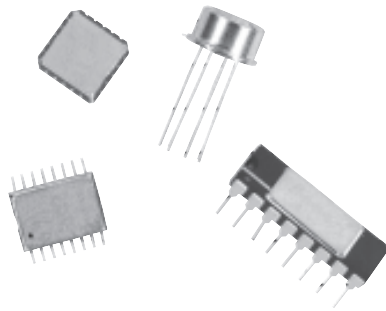


High Temperature, Hermetic Resistor Networks and Chips



The ULTRAFILM® Technology is particularly well adapted to high temperature applications up to + 200°C. The full range of standard products, in chip form or in hermetic packages, can be screened to be in conformity with the most stringent high temperature specifications.

FEATURES

- Minimize engineering expenses
- Shorten delivery time
- Cut down qualification costs

TYPICAL PERFORMANCE

	▲ ABS	TRACKING
TCR	10	2
	ABS	RATIO
TOL	0.05	0.02

SCHEMATIC			
	BARE CHIP (1)	HERMETIC PACKAGE (2)	
	RMK 33 HT	RMKT 33 HT	TO18
	RMK 55 HT RMK 515 HT	RMKT 55 HT RMKT 515 HT	TO18 TO18
	RMK 408 HT	RMKT 408 HT	DIP8
	RMK 508 HT	RMKD 508 HT	DIP8
	RMK 714 HT	RMKD 714 HT RMKS 714 HT RMKC 714 HT	DIP14 SO16 LCC16
	RMK 816 HT	RMKD 816 HT RMKS 816 HT RMKC 816 HT	DIP16 SO16 LCC16
	RMK 914 HT	RMKD 914 HT RMKS 914 HT RMKC 914 HT	DIP14 SO16 LCC16

1. See Bare chip data sheets for layouts .
2. See RMKD and RMKQ data sheets for dimensions.

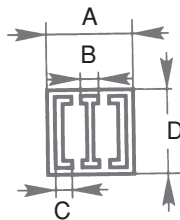
THROUGH HOLE

STANDARD ELECTRICAL SPECIFICATIONS

TEST	SPECIFICATIONS	CONDITIONS	
MATERIAL	ULTRAFILM®		
Resistance Range	1KΩ to 250KΩ		
TCR:	Tracking	± 1ppm/°C (2ppm/°C Max.)	
	Absolute	± 10ppm/°C	- 40°C to + 200°C
		± 15ppm/°C	- 55°C to + 200°C
Tolerance:	Ratio	± 0.02%	
	Absolute	± 0.05%	
Power Rating:	Resistor	0.050 Watt	
	Package	Variable, based on size	
Stability (ΔR Ratio)	≤ 500ppm typical	200 hrs. @ + 200°C	
Voltage Coefficient	0.1 ppm/Volt		
Working Voltage	50 Volts		
Operating Temperature Range	- 55°C to + 200°C		
Storage Temperature Range	- 55°C to + 200°C		
Noise	< - 35dB typical		
Thermal EMF	0.1μV/°C		
Shelf Life Stability	50ppm	1 year	

DIMENSIONS AND IMPRINTING in inches and millimeters

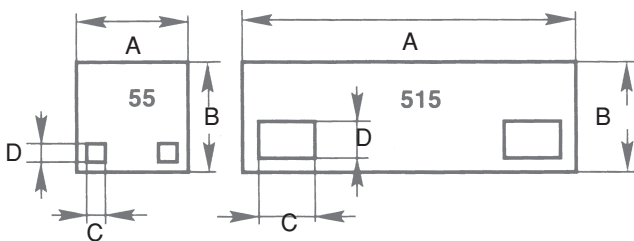
RMK 33 HT



BARE CHIP PACKAGING		
DIMENSION	INCHES	MILLIMETERS
A	0.030	0.76
B	0.004	0.10
C	0.005	0.13
D	0.030	0.76

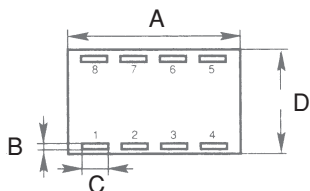
RMK 55 HT

RMK 515 HT



BARE CHIP PACKAGING				
DIMENSION	RMK 55 HT		RMK 515 HT	
	In.	mm	In.	mm
A	0.050	1.27	0.150	3.81
B	0.050	1.27	0.050	1.27
C	0.008	0.20	0.024	0.60
D	0.008	0.20	0.016	0.40

RMK 408 HT & RMK 508 HT

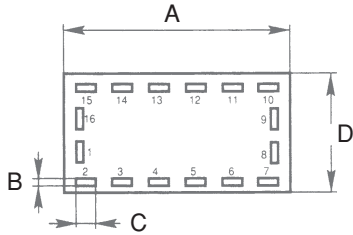


BARE CHIP PACKAGING		
DIMENSION	INCHES	MILLIMETERS
A	0.102	2.60
B	0.006	0.15
C	0.016	0.40
D	0.063	1.60



DIMENSIONS AND IMPRINTING in inches and millimeters

RMK 714 HT, RMK 816 HT, RMK 914 HT



BARE CHIP PACKAGING		
DIMENSION	INCHES	MILLIMETERS
A	0.134	3.40
B	0.005	0.13
C	0.009	0.24
D	0.067	1.70

MECHANICAL SPECIFICATIONS	
Resistive Element	Nichrome
Substrate Material	Al ₂ O ₃
Passivation	Silicon nitride
Bonding Pads	Aluminum
Packages	Hermetic side braze or LCC

THROUGH HOLE

How to Order

Series	Model	Ohmic Value	Absolute Tolerance	Ratio Tolerance
RMK	33 HT	1K	±0.1 %	±0.05 %
RMK RMKT RMKD RMKS RMKS RMKC	33 HT 55 HT 515 HT 408 HT 508 HT 714 HT 816 HT 914 HT	Ranges from 1K to 250K	±0.1 %	±0.05 % ±0.02 % ±0.01 %